



Description

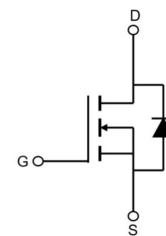
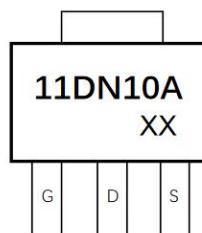
JMT N-channel Enhancement Mode Power MOSFET

Features

- 100V, 3A
- $R_{DS(ON)} < 125\text{m}\Omega$ @ $V_{GS} = 10\text{V}$
- $R_{DS(ON)} < 140\text{m}\Omega$ @ $V_{GS} = 4.5\text{V}$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired

Application

- Load Switch
- PWM Application
- Power management



SOT-89-3L top view

Marking and pin Assignment

Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
11DN10A	JMTN11DN10A	TAPING	SOT-89-3L	7inch	1000	40000

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		100	V
V_{GSS}	Gate-Source Voltage		± 20	V
I_D	Continuous Drain Current	$T_A = 25^\circ\text{C}$	3	A
		$T_A = 100^\circ\text{C}$	2	A
I_{DM}	Pulsed Drain Current ^{note1}		12	A
P_D	Power Dissipation	$T_A = 25^\circ\text{C}$	1.8	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		69	$^\circ\text{C}/\text{W}$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$

**Electrical Characteristics** ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	100	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=100\text{V}$, $V_{GS}=0\text{V}$,	-	-	1.0	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	1.0	1.5	2.5	V
$R_{DS(\text{on})}$ Note2	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}$, $I_D=3\text{A}$	-	95	125	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$, $I_D=2\text{A}$	-	100	140	$\text{m}\Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=25\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	765	-	pF
C_{oss}	Output Capacitance		-	38	-	pF
C_{rss}	Reverse Transfer Capacitance		-	33	-	pF
Q_g	Total Gate Charge	$V_{DS}=50\text{V}$, $I_D=2\text{A}$, $V_{GS}=10\text{V}$	-	18	-	nC
Q_{gs}	Gate-Source Charge		-	2.5	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	4	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=50\text{V}$, $I_D=3\text{A}$, $R_G=1.8\Omega$, $V_{GS}=10\text{V}$	-	7.5	-	ns
t_r	Turn-on Rise Time		-	6	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	21	-	ns
t_f	Turn-off Fall Time		-	9	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	3	-	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	12	-	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s=3\text{A}$	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	$I_F=3\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$	-	21	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	22	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

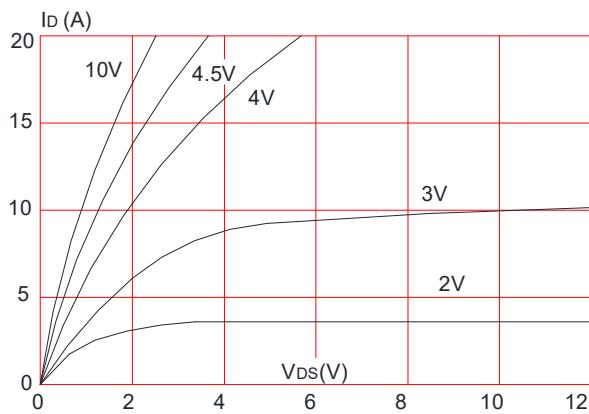


Figure 2: Typical Transfer Characteristics

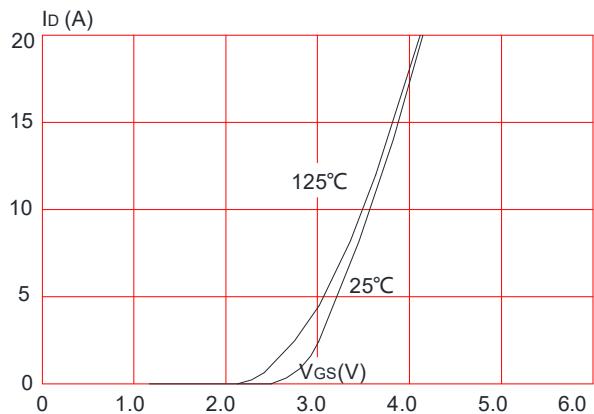


Figure 3: On-resistance vs. Drain Current

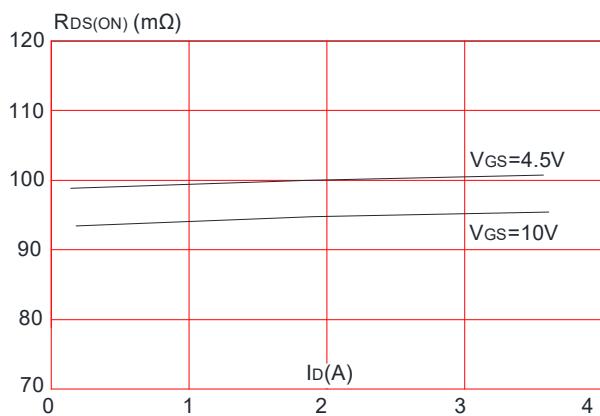


Figure 5: Gate Charge Characteristics

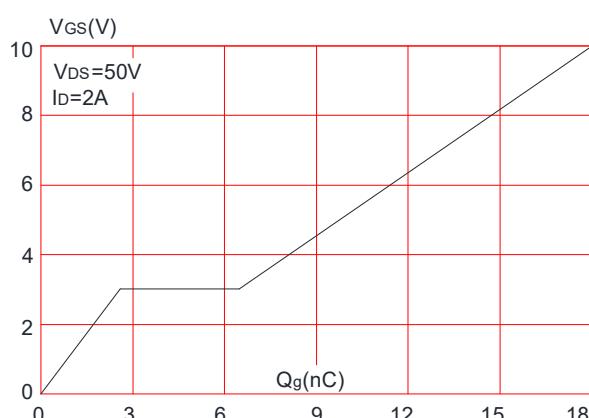


Figure 4: Body Diode Characteristics

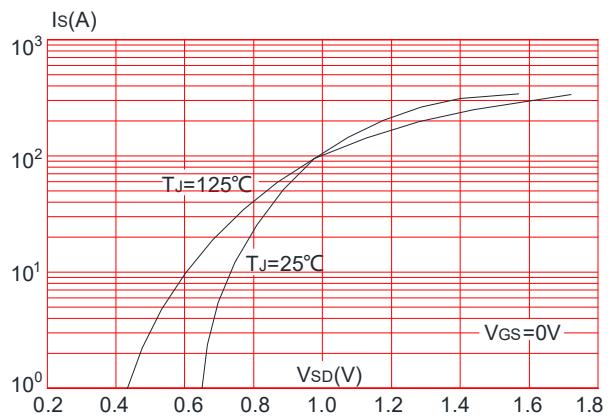


Figure 6: Capacitance Characteristics

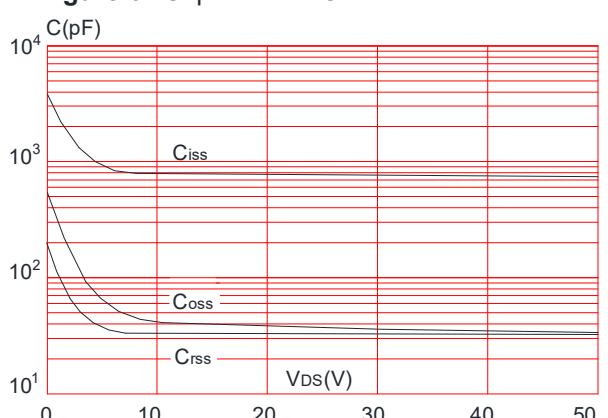


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

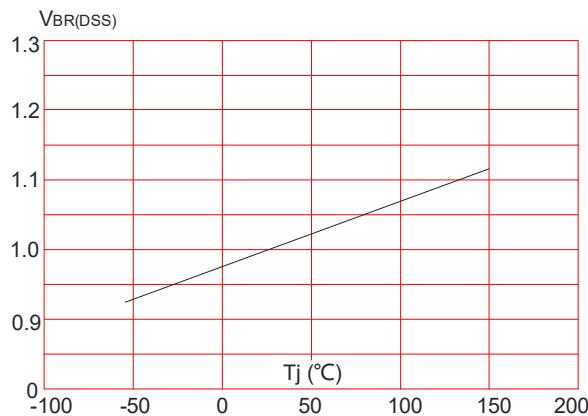


Figure 8: Normalized on Resistance vs. Junction Temperature

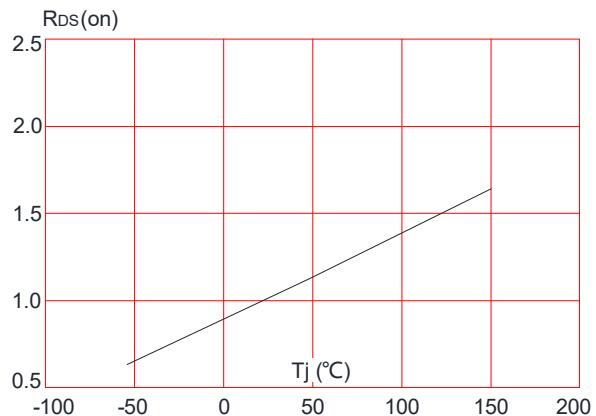


Figure 9: Maximum Safe Operating Area

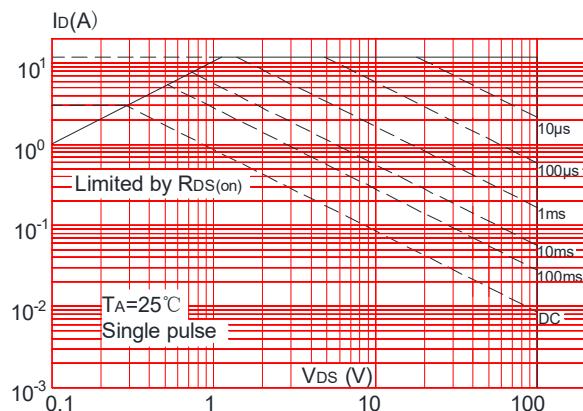


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

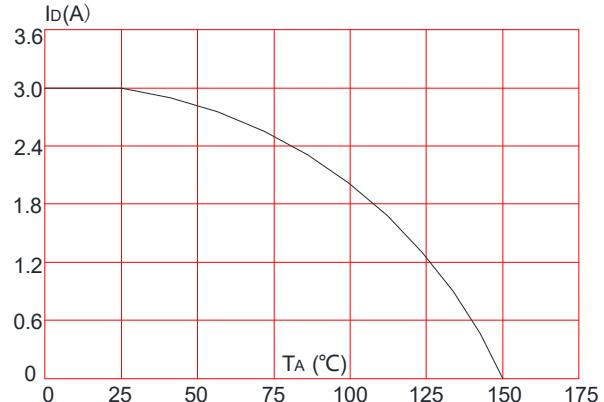
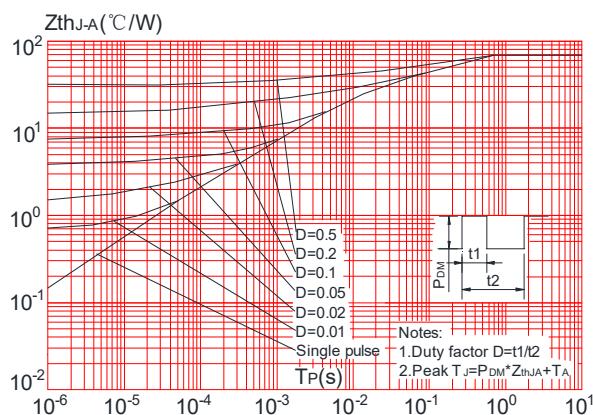


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



Test Circuit

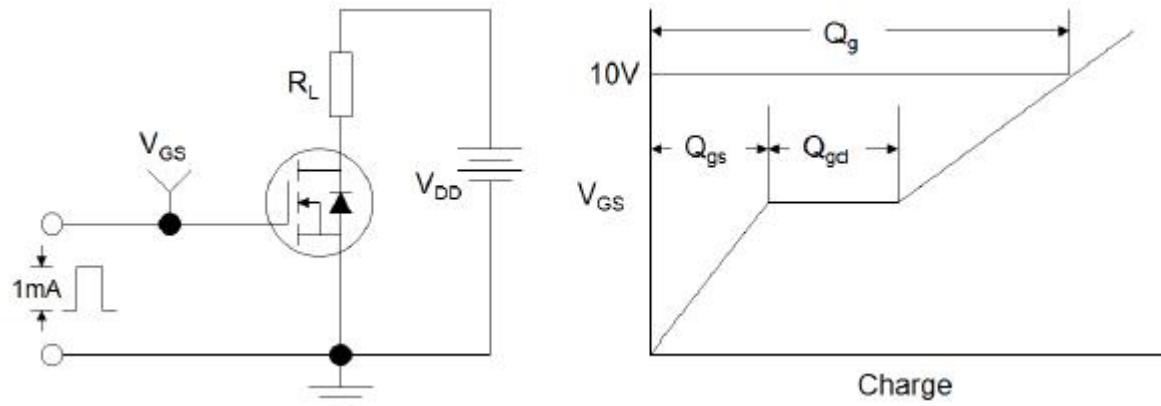


Figure1:Gate Charge Test Circuit & Waveform

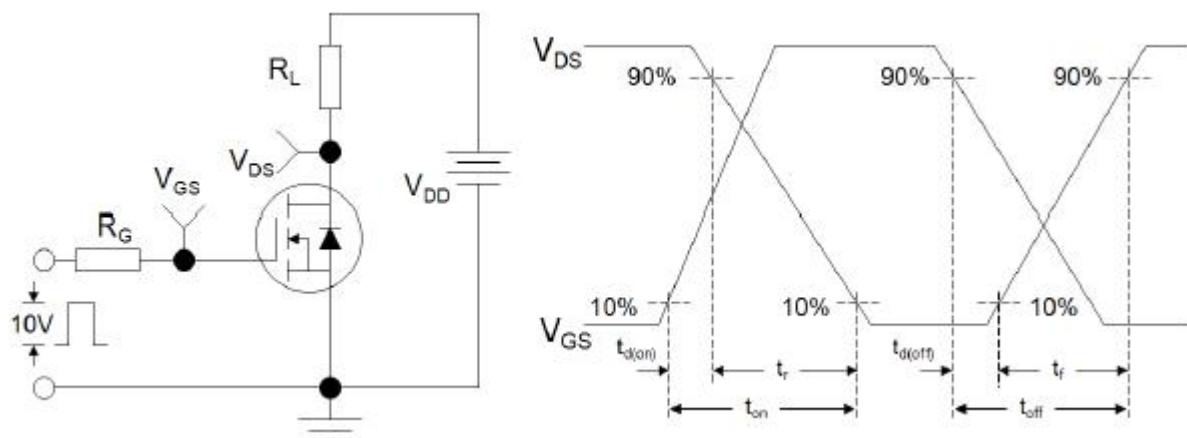


Figure 2: Resistive Switching Test Circuit & Waveforms

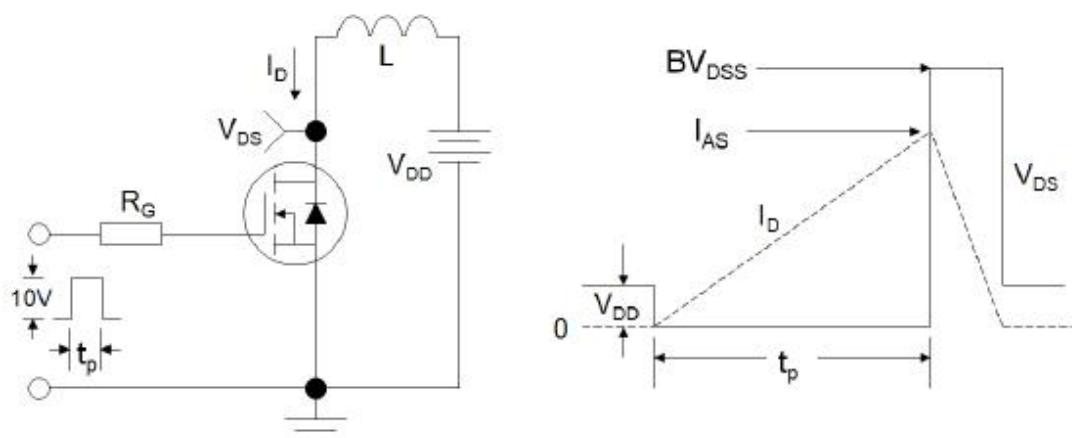
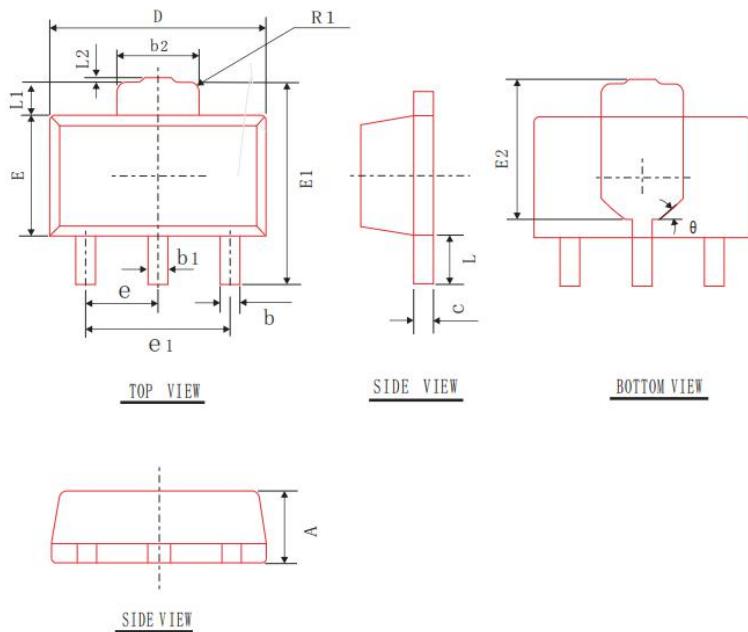


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms



Package Mechanical Data-SOT-89-3L

COMMON DIMENSIONS
(UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
A	1.40	1.50	1.60
b	0.36	0.40	0.50
b ₁	0.44	0.48	0.58
b ₂	1.60	1.70	1.80
c	0.35	0.40	0.45
D	4.40	4.50	4.60
E	2.40	2.50	2.60
E ₁	4.00	4.20	4.40
E ₂	2.65	2.85	3.05
e ₁	2.80	3.00	3.20
L	0.90	1.00	1.10
L ₁	0.60	0.70	0.80
L ₂	0.075 REF		
R ₁	0.2 BSC		
θ	45° TYP		
e	1.5 BSC		

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